SELF-PATTERNING OF PHOTO-ACTIVE DIELECTRIC MATERIALS FOR INTERCONNECT ISOLATION

ABSTRACT

In accordance with the objectives of the invention a new method is provided for the creation of an interconnect pattern. The invention provides for a layer of Photo-Active Dielectric (PAD) to be used for the insulation material in which the interconnect pattern is created, this without the use of an overlying exposure mask of photoresist.

Fig. 2